

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10657505			
<b>Filing Date:</b>	08-Sep-2003			
<b>Title of Invention:</b>	METHOD OF MANUFACTURING A CONTACT INTERCONNECTION LAYER CONTAINING A METAL AND NITROGEN BY ATOMIC LAYER DEPOSITION FOR DEEP SUB-MICRON SEMICONDUCTOR TECHNOLOGY			
<b>First Named Inventor/Applicant Name:</b>	Chil-Ming Wu			
<b>Filer:</b>	David M. Odell/Denise Wilson			
<b>Attorney Docket Number:</b>	TS01-1247			
Filed as Large Entity				
<b>Utility      Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
Utility Appt Issue fee	1501	1	1400	1400
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1700